

Applicant: T. S. Wong
Application No.: 10/618,985
Filed: July 14, 2003
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Docket No. J003US



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: T. S. Wong

Application No.: 10/618,985

Group Art Unit: 1732

Filed: July 14, 2003

Examiner: Stefan Staicovici

Title: THERMOPLASTIC MOLDING PROCESS

REDACTED DEPOSITED: December 22, 2005

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MS Patent Application.
Commissioner for Patents
P.O. Box 1450
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RESPONSE

Sir:

The October 4, 2005 Office Action ("Office Action") issued in connection with the above identified patent application finally rejected all of the pending claims. A Request for Continued Examination (RCE) of the application accompanies this Response. Please amend the RCE application as follows.